

## Product data sheet

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Other Data Body End termination Packaging Complies with Standard Notes: \*1 AC voltage at 50~60Hz \*2 Varistor voltage \*3 Capacitance

\*4 Maximum clamping voltage

\*5 Rated peak single pulse transient current

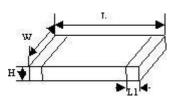
MS0402ESDA-XX HF

Semiconductor Compiance

ZnO Ag/Ni/Sn Tape IEC61000-4-2、IEC61000-4-5

Measured at 1mA DC Measured at f=1kHz,Vrms=0.5V Measured at 1A by 8/20µs Pulse Measured by 8/20µs Pulse

Size:				Unit: mm
PKG	Length (L)	Width (W)	High (H)	Termination (L1)
0402	1.00±0.20	0.50±0.20	0.70 (max)	$0.30 \pm 0.20$



Standards			
MS	<u>0402</u>	<u>ESDA</u>	XX
$\bigcirc$	2	3	4
(1)production	n series:	msksemi	

②size: 0402

③type: ESD高分子保护器件

(4) V<sub>DC</sub>: 5V 9V 12V 14V 18V 24V

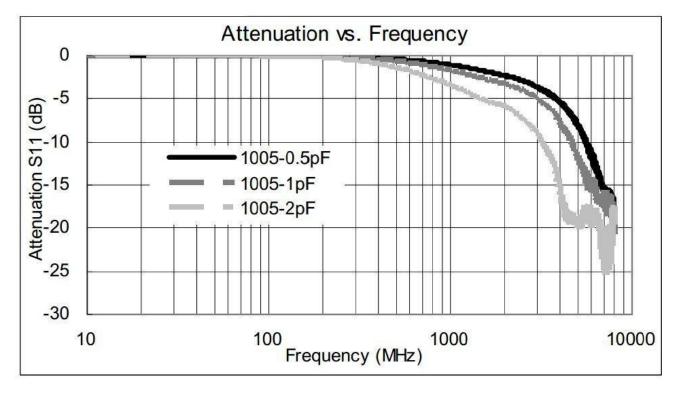
Technical Data	Symbol	Value	Unit
Maximum allowable continuous DC voltage	V <sub>DC</sub>	5.0	V
Varistor voltage Measured*2	VB	130	V
Varistor voltage tolerance		±20	%
Typical capacitance value measured*3	С	1.0	pF
Typical capacitance value tolerance		±0.3	PF
Maximum clamping voltage measured*4	Vc	250	V

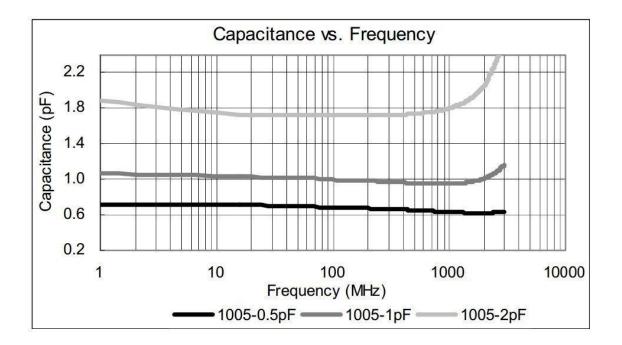
Reference Data			
Response time	T rise	<1	ns
Leakage current at $V_B \times 80\%$ (At initial state)	I <sub>LVB</sub>	<20	μA
Leakage current at V <sub>B</sub> ×80%(After reliability Test)	I <sub>LVBA</sub>	<100	μA
Operating ambient temperature		—	°C
		55~+125	
Storage temperature		—	°C
		40~+125	
Reflow temperature profile(Recommend)		260	°C





## **V-I characteristic**

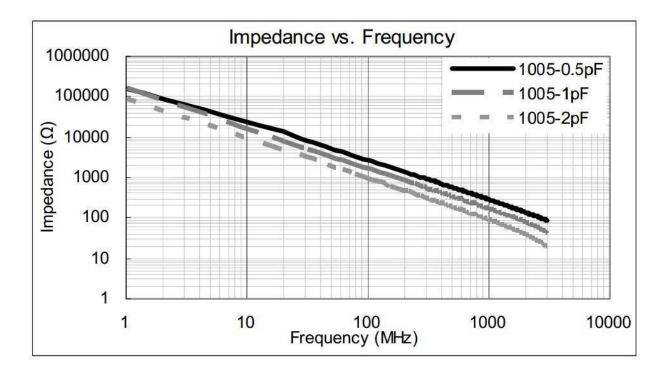




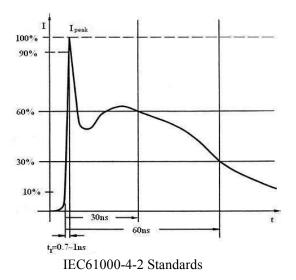




Semiconductor Compiance



**Esd Wave Form** 



SEVERITY LEVEL	AIRDIRCHARGE	DIRECT ISCHARGE
1	2 kV	2 kV
2	4 kV	4 kV
3	8 kV	6 kV
4	15 kV	8 kV

IEC61000-4-2 Compliant ESD Current Pulse Waveform





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